

PIN FIN &
ELLIPTICAL
HEAT SINKS



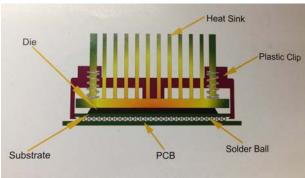
Wakefield-Vette's 901-910 Series Heat Sinks for Chipset can match up to devices from Intel, Broadcom, Xilinx. TI, Motorola and many more! These heat sinks are designed for air flow applications. Enclosed pages have thermal performance data for natural forced convection values.

4 Springs at each corner





wakefield-vette New Chip Set Heat Sinks



Wakefield-Vette heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.







Material: AL 6063

Finish: Black Anodize

All dimensions in millimeters (mm)

Part Numbering System

<u>Series</u>	<u>Chip Size</u>	<u>Construction</u>	<u>Height</u>	Spring Type *	<u>Finish</u>	<u>Interface</u>
a S						# 2
<u>901-</u>	<u>19-</u>	<u>1-</u>	<u>12-</u>	<u>1-</u>	<u>B-</u>	<u>1</u>
XXX	XX	Χ	XX	Χ	Χ	Χ

901	19	1= Eliptical Fin	12 = 11.6	1 = .9-2.1 CST	B = BLK ANO	0 = None
902	21	2= Pin Fin	15 = 14.6	2 = 2.2-3.4 CST		1 = T725
903	23		18 = 17.6		J.	
904	27		21 = 20.6			
905	29		23 = 22.6			
906	31		28 = 27.6			
907	33		33 = 32.6			
908	35	•		•		
909	37.5			*N -+- \\\/	-4!	-1-1

*Note: When selecting part number chip set thickness (CST) relates to spring selection!









THERMAL PERFORMANCE



FORCED CONVECTION (C/W) 200 LFM 400 LFM 600 LFM 6.63 C/W 5.09 C/W 4.38 C/W 6.12 C/W 4.63 C/W 3.95 C/W 5.67 C/W 4.17 C/W 3.58 /CW 5.28 C/W 3.87 C/W 3.24 C/W 4.89 C/W 3.58 C/W 3.06 C/W 4.38 C/W 3.26 C/W 2.80 C/W
6.63 C/W 5.09 C/W 4.38 C/W 6.12 C/W 4.63 C/W 3.95 C/W 5.67 C/W 4.17 C/W 3.58 /CW 5.28 C/W 3.87 C/W 3.24 C/W 4.89 C/W 3.58 C/W 3.06 C/W
6.12 C/W 4.63 C/W 3.95 C/W 5.67 C/W 4.17 C/W 3.58 /CW 5.28 C/W 3.87 C/W 3.24 C/W 4.89 C/W 3.58 C/W 3.06 C/W
5.67 C/W 4.17 C/W 3.58 /CW 5.28 C/W 3.87 C/W 3.24 C/W 4.89 C/W 3.58 C/W 3.06 C/W
5.28 C/W 3.87 C/W 3.24 C/W 4.89 C/W 3.58 C/W 3.06 C/W
4.89 C/W 3.58 C/W 3.06 C/W
4.38 C/W 3.26 C/W 2.80 C/W
4.04 C/W 2.98 C/W 2.62 C/W
5.81 C/W 3.86 C/W 3.16 C/W
5.3 C/W 3.5 C/W 2.89 C/W
4.95 C/W 3.35 C/W 2.66 C/W
4.61 C/W 3.111 C/W 2.47 C/W
4.32 C/W 2.91 C/W 2.32 C/W
3.89 C/W 2.61 C/W 2.09 C/W
3.57 C/W 2.37 C/W 1.95 C/W
4.75 C/W 3.31 C/W 2.79 C/W
4.38 C/W 3.05 C/W 2.53 C/W
4.07 C/W 2.81 C/W 2.32 C/W
3.84 C/W 2.57 C/W 2.11 C/W
3.59 C/W 2.4 C/W 1.97 C/W
3.22 C/W 2.17 C/W 1.8 C/W
2.93 C/W 1.95 C/W 1.64 C/W
4.34 C/W 3 C/W 2.53 C/W
4.05 C/W 2.76 C/W 2.29 C/W
3.73 C/W 2.5 C/W 2.07 C/W
3.43 C/W 2.31 C/W 1.9 C/W
3.21 C/W 2.11 C/W 1.71 C/W
2.89 C/W 1.84 C/W 1.51 C/W
2.62 C/W 1.66 C/W 1.35 C/W
4.09 C/W 2.74 C/W 2.25 C/W
3.81 C/W 2.52 C/W 2.02 C/W
3.56 C/W 2.31 C/W 1.84 C/W
3.3 C/W 2.12 C/W 1.65 C/W
3.06 C/W 1.91 C/W 1.49 C/W
2.72 C/W 1.69 C/W 1.33 C/W
2.47 C/W 1.49 C/W 1.18 C/W

Thermal Cooling Solutions from SMART to FINISH





THERMAL PERFORMANCE



	PIN FIN						ELLIPTICAL FIN				
	HT	CHIP	NATURAL	FORCED CONVECTION (C/W)		NATURAL FORCED CONVECTION (ON (C/W)		
<u></u>		SIZE	CONVECTION	200 LFM	400 LFM	600 LFM	CONVECTION	200 LFM	400 LFM	600 LFM	
906	12	31mm	10.71 C/W	3.49 C/W	2.28 C/W	1.69 C/W	12.02 C/W	3.37 C/W	2.25 C/W	1.87 C/W	
[15	31mm	10.14 C/W	3.18 C/W	2.03 C/W	1.5 C/W	11.43 C/W	3.13 C/W	2.02 C/W	1.66 C/W	
[18	31mm	9.57 C/W	2.93 C/W	1.86 C/W	1.33 C/W	10.85 C/W	2.85 C/W	1.79 C/W	1.45 C/W	
[21	31mm	9.01 C/W	2.72 C/W	1.69 C/W	1.2 C/W	10.27 C/W	2.63 C/W	1.63 C/W	1.31 C/W	
[23	31mm	8.88 C/W	2.5 C/W	1.54 C/W	1.07 C/W	9.88 C/W	2.44 C/W	1.5 C/W	1.19 C/W	
[28	31mm	8.56 C/W	2.26 C/W	1.38 C/W	.96 C/W	8.93 C/W	2.21 C/W	1.36 C/W	1.05 C/W	
[33	31mm	8.24 C/W	2.09 C/W	1.27 C/W	.88 C/W	7.98 C/W	2.02 C/W	1.19 C/W	.93 C/W	
907	12	33mm	10.37 C/W	3.32 C/W	2.18 C/W	1.62 C/W	11.56 C/W	3.23 C/W	2.09 C/W	1.73 C/W	
[15	33mm	9.82 C/W	3.14 C/W	1.99 C/W	1.45 C/W	11 C/W	2.97 C/W	1.88 C/W	1.54 C/W	
[18	33mm	9.28 C/W	2.89 C/W	1.78 C/W	1.3 C/W	10.45 C/W	2.69 C/W	1.7 C/W	1.37 C/W	
	21	33mm	8.73 C/W	2.67 C/W	1.60 C/W	1.13 C/W	9.9 C/W	2.5 C/W	1.52 C/W	1.22 C/W	
	23	33mm	8.60 C/W	2.45 C/W	1.43 C/W	.99 C/W	9.54 C/W	2.3 C/W	1.37 C/W	1.08 C/W	
[28	33mm	8.27 C/W	2.24 C/W	1.28 C/W	.87 C/W	8.62 C/W	2.08 C/W	1.23 C/W	.98 C/W	
	33	33mm	7.94 C/W	2.03 C/W	1.15 C/W	.77 C/W	7.71 C/W	1.89 C/W	1.08 C/W	.86 C/W	
908	12	35mm	10.03 C/W	3.06 C/W	1.97 C/W	1.49 C/W	11.1 C/W	3.07 C/W	2.07 C/W	1.64 C/W	
	15	35mm	9.5 C/W	2.85 C/W	1.81 C/W	1.34 C/W	10.58 C/W	2.79 C/W	1.87 C/W	1.46 C/W	
l	18	35mm	8.98 C/W	2.6 C/W	1.64 C/W	1.19 C/W	10.06 C/W	2.54 C/W	1.69 C/W	1.27 C/W	
	21	35mm	8.46 C/W	2.4 C/W	1.5 C/W	1.07 C/W	9.53 C/W	2.35 C/W	1.52 C/W	1.15 C/W	
[23	35mm	8.32 C/W	2.19 C/W	1.34 C/W	.97 C/W	8.75 C/W	2.13 C/W	1.35 C/W	1.01 C/W	
	28	35mm	7.99 C/W	1.97 C/W	1.19 C/W	.83 C/W	7.93 C/W	1.94 C/W	1.19 C/W	.86 C/W	
- 1	33	35mm	7.65 C/W	1.82 C/W	1.06 C/W	.7 C/W	7.11 C/W	1.69 C/W	1.02 C/W	.72 C/W	
909	12	37.5mm		2.93 C/W	1.90 C/W	1.36 C/W	10.52 C/W	3.11 C/W	2.01 C/W	1.61 C/W	
l	15	37.5mm		2.71 C/W	1.72 C/W	1.19 C//W	10.04 C/W	2.82 C/W	1.79 C/W	1.41 C/W	
l l	18	37.5mm		2.52 C/W	1.53 C/W	1.05 C/W	9.56 C/W	2.59 C/W	1.59 C/W	1.22 C/W	
- 1	21	37.5mm		2.25 C/W	1.36 C/W	.88 C/W	9.08 C/W	2.38 C/W	1.41 C/W	1.06 C/W	
l	23	37.5mm		2.04 C/W	1.2 C/W	.75 C/W	8.75 C/W	2.15 /CW	1.24 C/W	.94 C/W	
- 1	28	37.5mm	TATABARAN SANGER OF CO.	1.82 C/W	1.01 C/W	.63 C/W	7.93 C/W	1.88 C/W	1.08 C/W	.8 C/W	
ı.	33	37.5mm	The second secon	1.6 C/W	.87 C/W	.52 C/W	7.11 C/W	1.64 C/W	.93 C/W	.68 C/W	
910	12	40mm	9.18 C/W	2.84 C/W	1.86 C/W	1.36 C/W	9.95 C/W	3.09 C/W	1.93 C/W	1.56 C/W	
ı.	15	40mm	8.71 C/W	2.64 C/W	1.65 C/W	1.18 C/W	9.51 C/W	2.77 C/W	1.73 C/W	1.37 C/W	
Į	18	40mm	8.24 C/W	2.4 C/W	1.44 C/W	.98 C/W	9.06 C/W	2.74 C/W	1.52 C/W	1.17 C/W	
Į	21	40mm	7.77 C/W	2.21 C/W	1.27 C/W	.86 C/W	8.62 C/W	2.22 C/W	1.35 C/W	.99 C/W	
Į.	23	40mm	7.63 C/W	2 C/W	1.15 C/W	.73 C/W	8.3 C/W	2.01C/W	1.19 C/W	.87 C/W	
Į.	28	40mm	7.27 C/W	1.77 C/W	.99 C/W	.62 C/W	7.55 C/W	1.8 C/W	1.04 C/W	.75 C/W	
l	33	40mm	6.92 C/W	1.58 C/W	.85 C/W	.51 C/W	6.78 C/W	1.61 C/W	.88 C/W	.64 C/W	

Thermal Cooling Solutions from SMART to FINISH





Wave Form: Half sine wave

Acceleration: 50 g Duration Time: 11 ms

No. of Shock: Each axis 3 times Shock Direction: ±X, ±Y, ±Z axis

Reliability & Communication Testing

Instruments

Random Vibration test

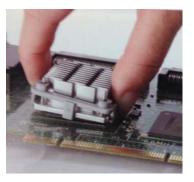
Frequency: 5 Hz to 500 Hz Acceleration: 3.13 grms P.S.D: 0.01 g2/HZ (5 Hz) 0.02 g2/HZ (20 Hz to 500 Hz)

Test Axis: X, Y, Z axis

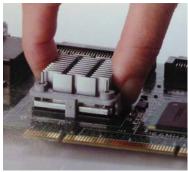
Test Time: 10 mins (Each axis)

Total Test Time: 30 mins

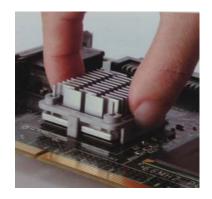




STEP 1: Center heat Sink onto BGA. Tilt and hook one side of the clip under the BGA chip.



STEP 2: Press down the other side of clip to snap it onto the BGA chip.



STEP: 3 Make sure the stop pin is not on top of the chip set. Installation Done!







Contact Us / Corporate Location Information

Wakefield-Vette is Global. Global presence means our engineering, design, sales and support are close to our customers, in the Americas, Europe, Middle East and Asia. It mean multi-national manufacturing and delivery. And it means a global Wakefield-Vette supply chain that can deliver, and provide support quickly, anywhere, with the highest quality solutions.

Contact sales for a list of Distributors that carry stock.

East Coast Operations

New Hampshire

33 Bridge Street

Pelham.NH 03076

Phone: 603-635-2800

Fax: 603-635-1900

Info@wakefield-vette.com

(Wakefield-Vette Headquarters)

2013 Wakefield-Vette. All rights reserved. Information is subject to change without notice. Wakefield-Vette assumes no liability for the errors that may appear in this document.

